

FH30110G

30V N-Channel Enhancement Mode Power MOSFET

General Description

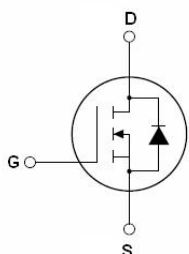
FH30110G uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

Applications

- Power Management Switches
- DC/DC Converter

Features

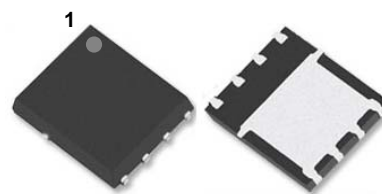
- $V_{DS} = 30\text{ V}$, $I_D = 108\text{ A}$
 $R_{DS(on)}(\text{Typ}) = 3.0\text{ m}\Omega @V_{GS} = 10\text{ V}$
 $R_{DS(on)}(\text{Typ}) = 3.6\text{ m}\Omega @V_{GS} = 4.5\text{ V}$
- Green Device Available
- 100% EAS Guaranteed
- Low Gate Charge
- Low $R_{DS(ON)}$



Schematic diagram



Marking and pin Assignment



PDFN5X6-8L top and bottom view

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	108	A
	$T_C = 100^\circ\text{C}$		68	
Pulsed Drain Current ¹		I_{DM}	432	A
Single Pulse Avalanche Energy ²		EAS	80	mJ
Total Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	69	W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	$R_{\theta JA}$	62	$^\circ\text{C/W}$
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	1.8	$^\circ\text{C/W}$

Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	30	-	-	V
Gate-body Leakage Current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T _J =25°C	V _{DS} = 30V, V _{GS} = 0V	-	-	1	μA
	T _J =100°C		-	-	100	
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1	1.6	2.5	V
Drain-Source On-Resistance ⁴	R _{DS(on)}	V _{GS} = 10V, I _D = 30A	-	3	4	mΩ
		V _{GS} = 4.5V, I _D = 15A	-	3.6	5	
Forward Transconductance ⁴	g _{fs}	V _{DS} = 10V, I _D = 30A	-	125	-	S
Dynamic Characteristics⁵						
Input Capacitance	C _{iss}	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz	-	2560	-	pF
Output Capacitance	C _{oss}		-	416	-	
Reverse Transfer Capacitance	C _{rss}		-	289	-	
Gate Resistance	R _g	f = 1MHz	-	2	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q _g	V _{GS} = 4.5V, V _{DS} = 15V, I _D = 30A	-	32	-	nC
Gate-Source Charge	Q _{gs}		-	6	-	
Gate-Drain Charge	Q _{gd}		-	12.5	-	
Turn-On Delay Time	t _{d(on)}	V _{GS} = 10V, V _{DD} = 15V, R _G = 3Ω, I _D = 30A	-	12.5	-	ns
Rise Time	t _r		-	28	-	
Turn-Off Delay Time	t _{d(off)}		-	65	-	
Fall Time	t _f		-	53	-	
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	I _S = 1A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current	T _C =25°C	I _S	-	-	108	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
2. The EAS data shows Max. rating. The test condition is V_{DD}= 25V, V_{GS}=10V, L= 0.1mH, I_{AS}= 40A.
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics

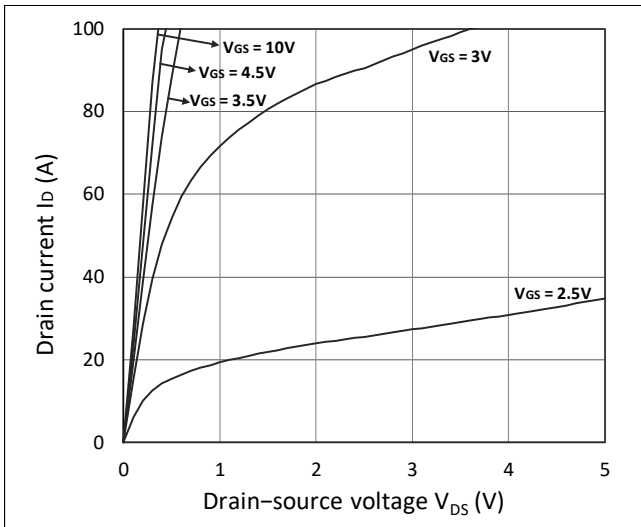


Figure 1. Output Characteristics

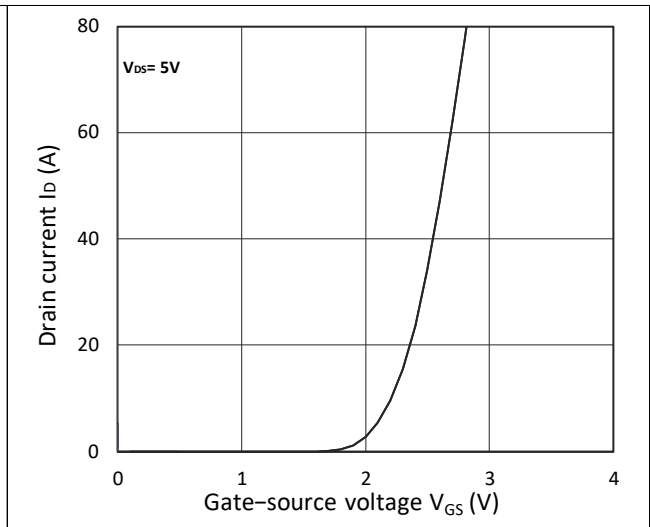


Figure 2. Transfer Characteristics

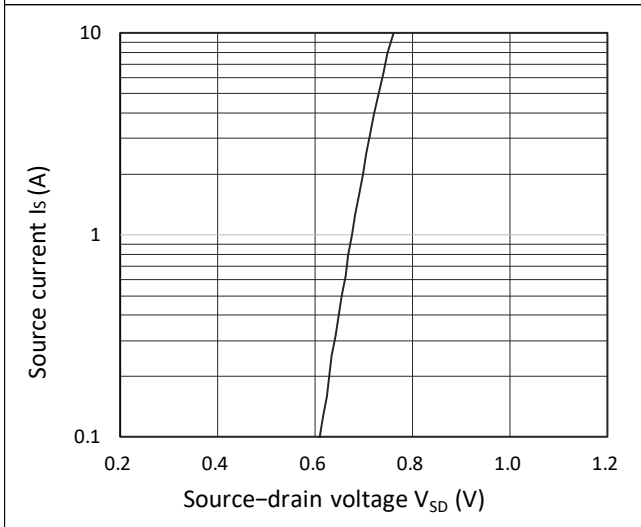


Figure 3. Forward Characteristics of Reverse

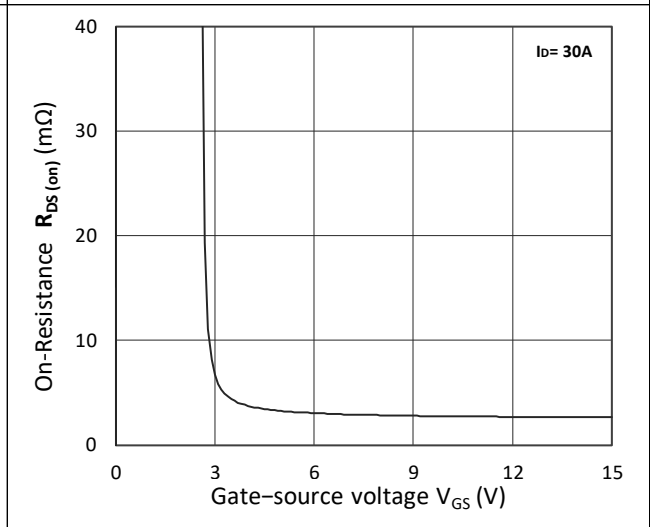


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

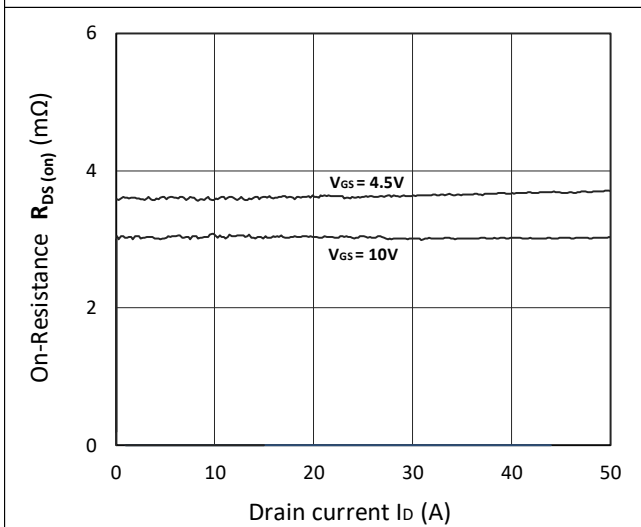


Figure 5. $R_{DS(ON)}$ vs. I_D

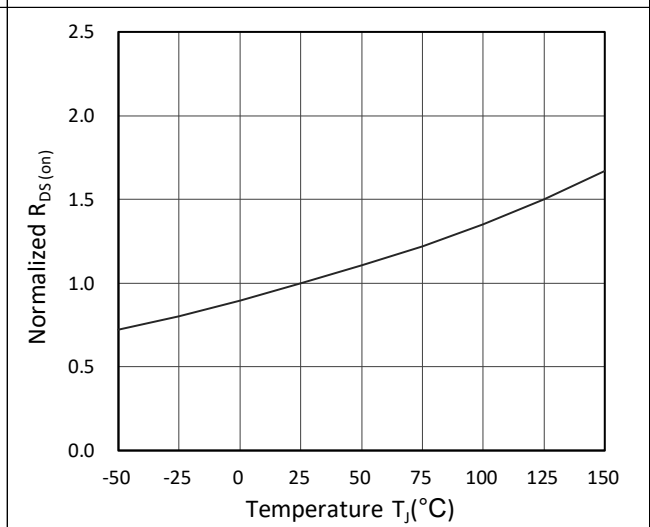


Figure 6. Normalized $R_{DS(ON)}$ vs. Temperature

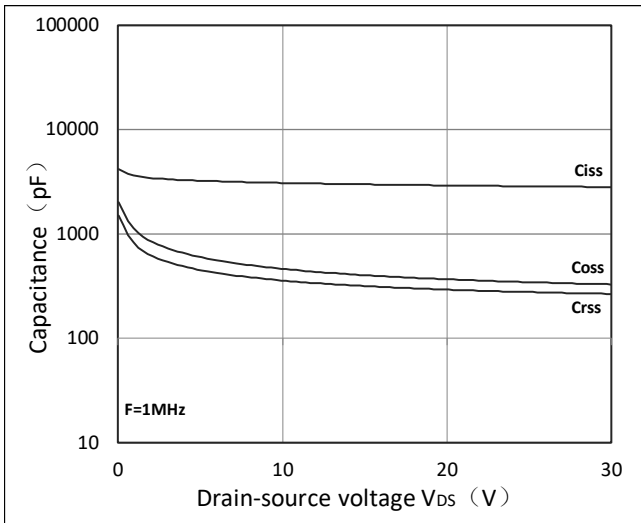


Figure 7. Capacitance Characteristics

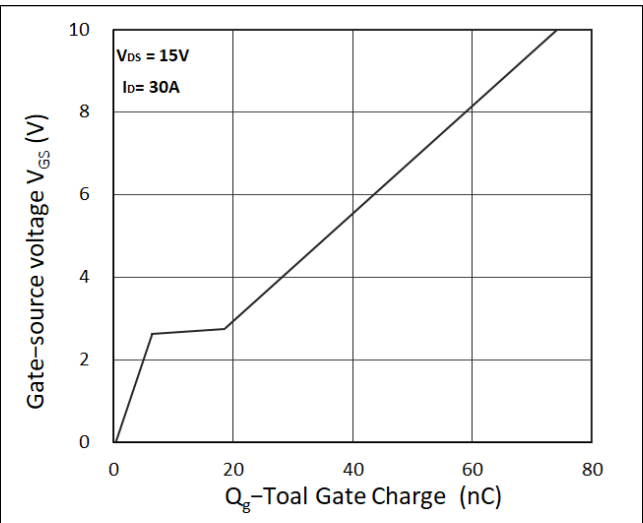


Figure 8. Gate Charge Characteristics

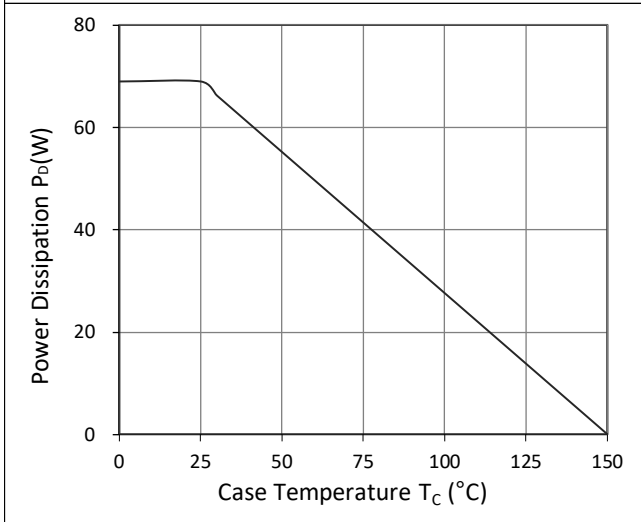


Figure 9. Power Dissipation

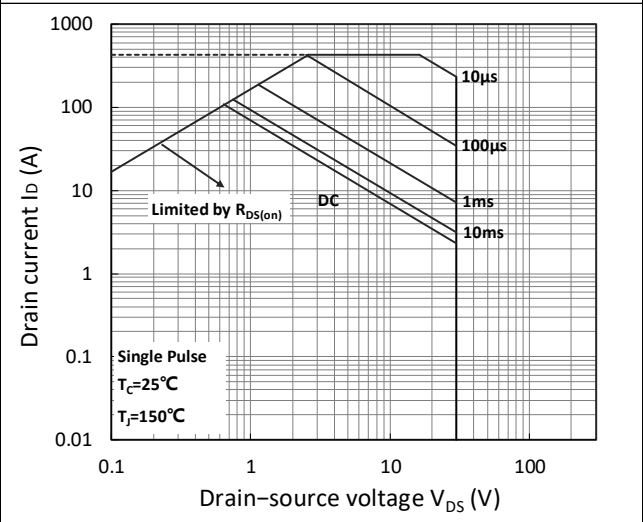


Figure 10. Safe Operating Area

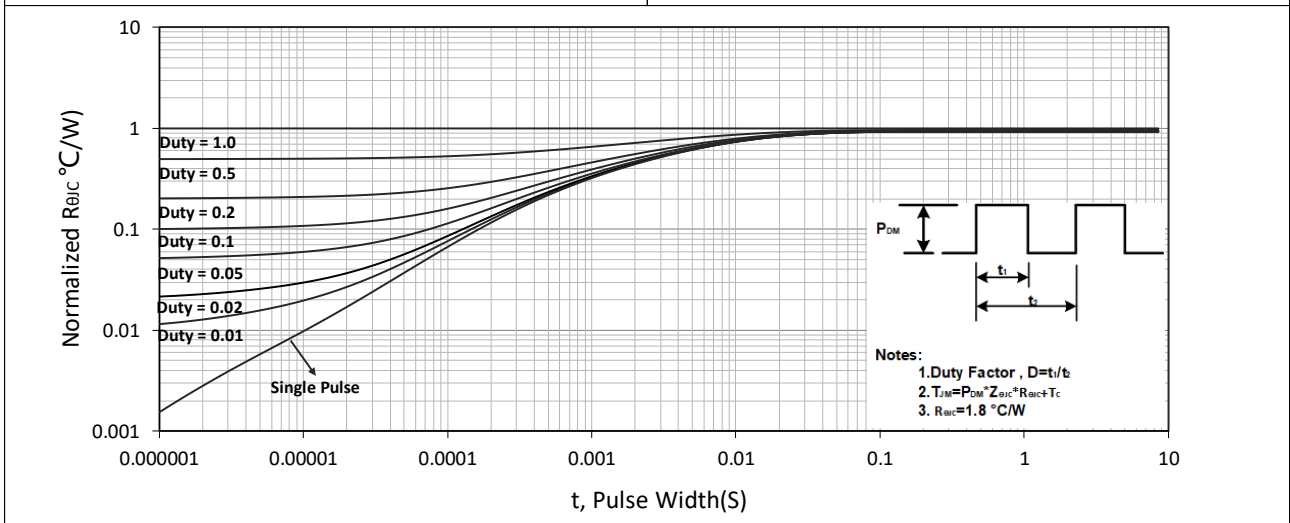


Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

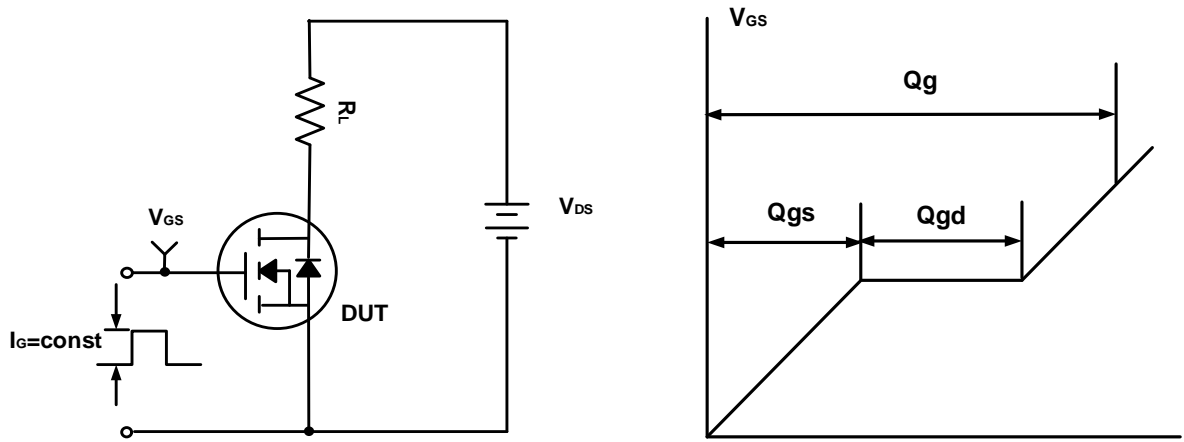


Figure A. Gate Charge Test Circuit & Waveforms

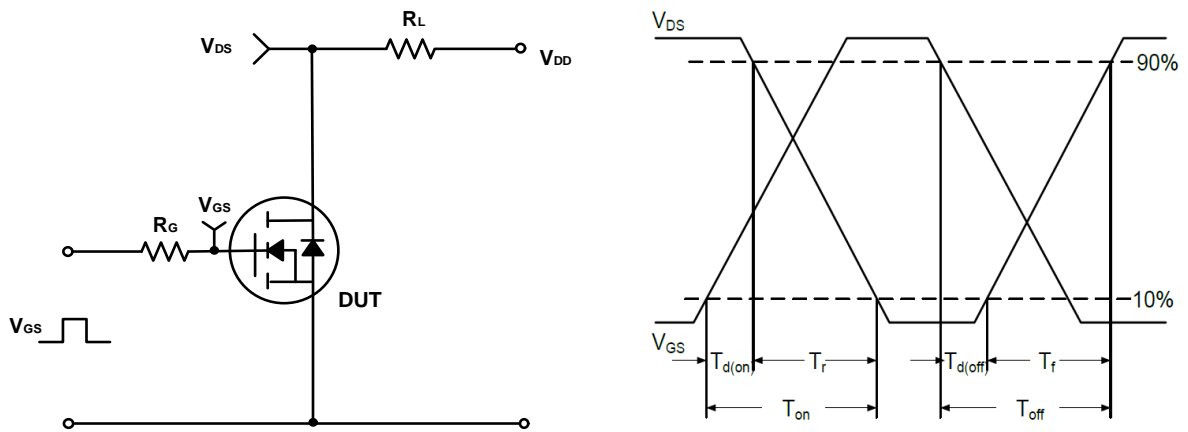


Figure B. Switching Test Circuit & Waveforms

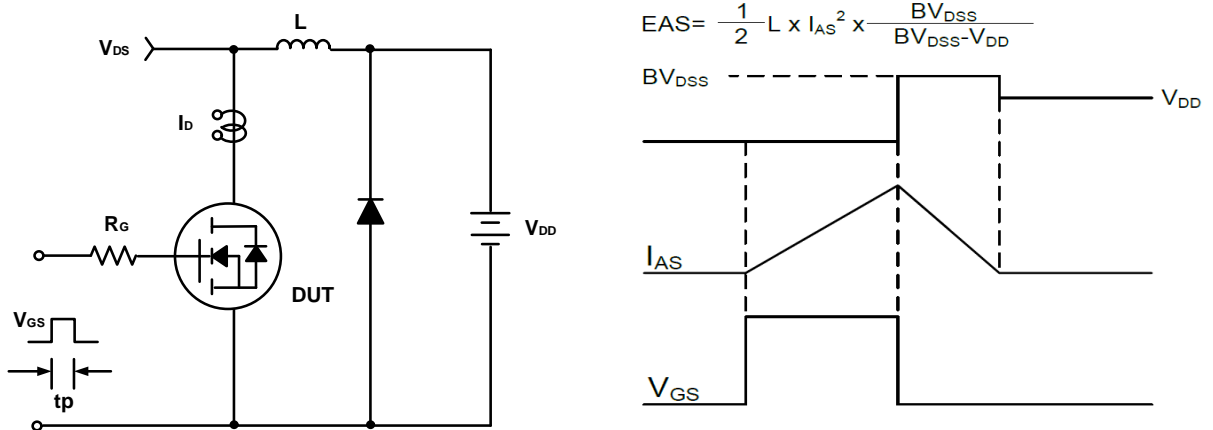
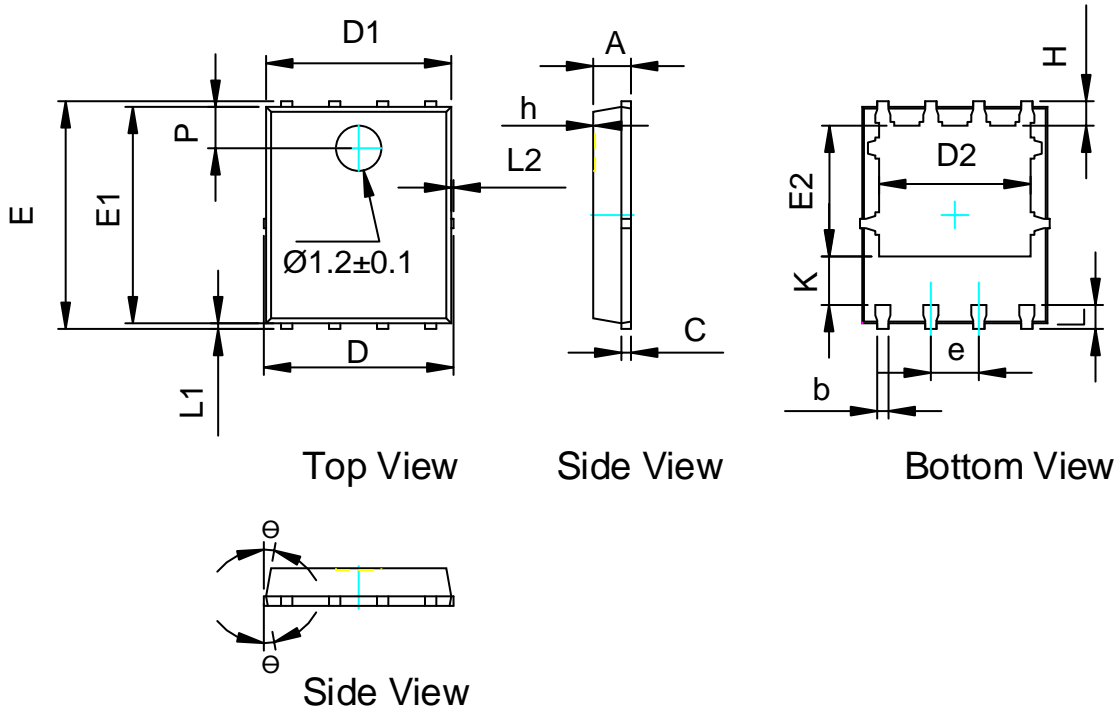


Figure C. Unclamped Inductive Switching Circuit & Waveforms

Package Outlines



SYMBOL	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.20	0.30	0.40
c	0.21	0.25	0.34
D	-	-	5.10
D1	4.80	4.90	5.00
D2	3.91	4.01	4.11
e	1.27 BSC		
E	5.90	6.00	6.10
E1	5.65	5.75	5.85
E2	3.375	3.475	3.575
H	0.55	0.65	0.75
h	-	-	0.05
K	1.20	-	-
L	0.55	0.65	0.75
L1	0.05	0.15	0.25
L2	-	-	0.12
Θ	8°	10°	12°
P	1.00	1.10	1.20

COMMON DIMENSIONS: (UNITS OF MEASURE = MILLIMETER)